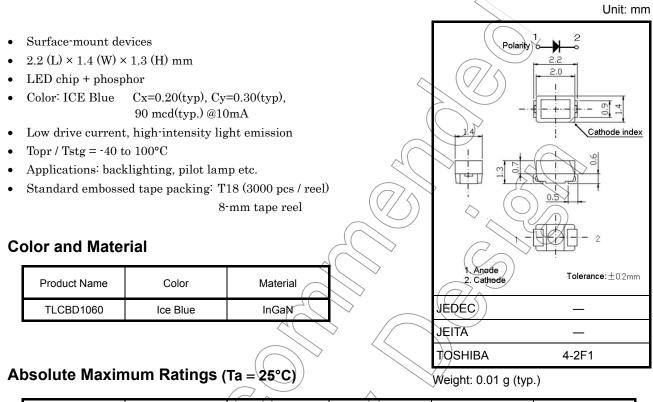
TOSHIBA LED Lamp

TLCBD1060(T18)

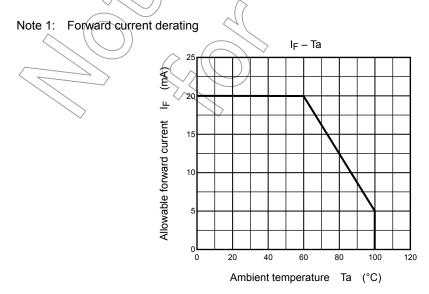
Panel Circuit Indicator



Product Name	Forward Current I _F (mA) Please see Note 1	Reverse Voltage V _R (V)	Power Dissipation	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLCBD1060	_20 (//) 4	76	-40 to 100	-40 to 100

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

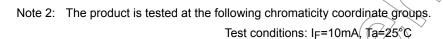


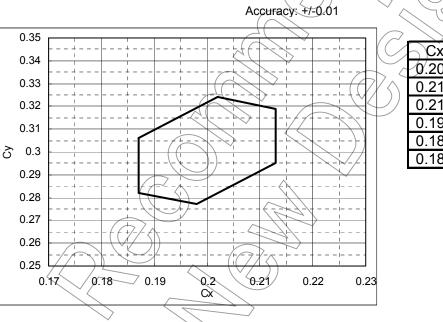
Electrical Characteristics (Ta = 25°C)

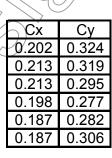
Product Name	Forward Voltage V _F				Reverse Current I _R	
Floduct Name	Min	Тур.	Max	IF	Max	V _R
TLCBD1060	2.5	3.0	3.8	10	10	4
Unit	V			mA	μA	V

Optical Characteristics (Ta = 25°C)

plical offalacteristics (1a – 2			
Item	Symbol	Test condition Min. Typ. Max.	Unit
Chromaticity coordinate	C _x	I _F = 10 mA (Note 2)	—
	Cy	I _F = 10 mA (Note 2)	—
Luminous intensity	IV	I _F = 10 mA (Note 3) 40 90 200	mcd









	\bigcirc				0)Ta=25℃
\wedge (\bigcirc)	Product	Luminous Intensity I_V				
		hame	Min.	Тур.	Max.	١ _F
	TLCBD700	30(T18)	40		200	
		PA	40	—	80	10
\searrow		∕∕ _{QA}	63	—	125	10
		RA	100	_	200	
	Uni		mcd		mA	

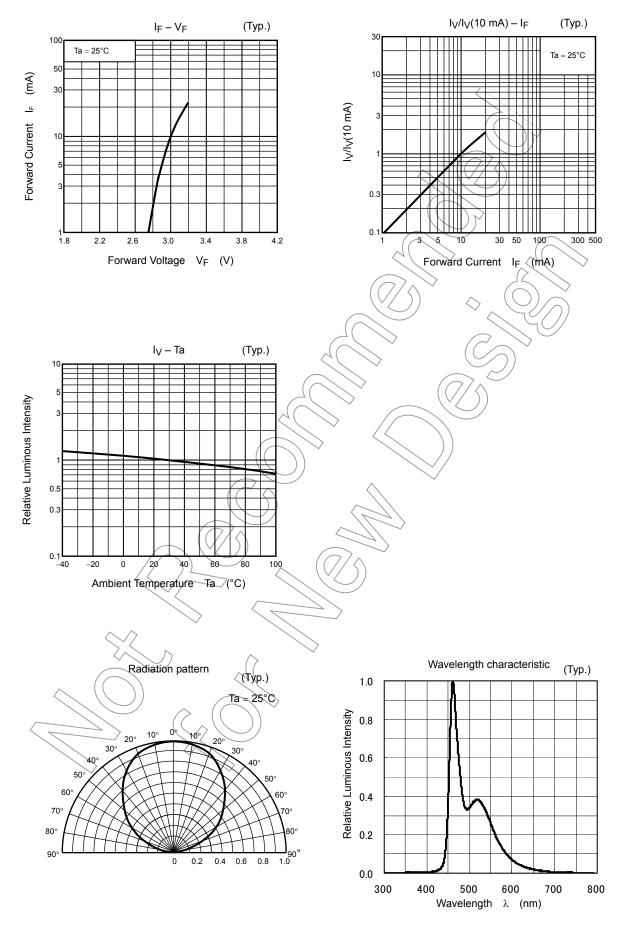
The specification on the above table is used for Iv classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

The cautions

- ESD withstand voltage according to MIL STD 883D, Method 3015.7 : ≥1000V
- When handling this LED, take the following measures to prevent the LED from being damaged or otherwise adversely affected.
 - 1) Use a conductive tablemat and conductive floor mat, and ground the workbench and floor.
 - 2) Operators handling laser diodes must be grounded via a high resistance (about 1MΩ). A conductive strap is good for this purpose.
 - 3) Ground all tools including soldering irons.

- This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

TLCBD1060



roshiba

Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

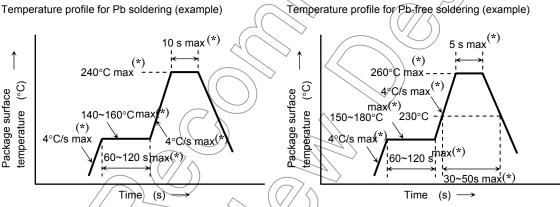
- 1. This moisture proof bag may be stored unopened within 12 months at the following conditions. Temperature: 5°C~30°C Humidity: 90% (max)
- 2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
- 3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel. After baking, use the baked devices within 72 hours, but perform baking only once. Baking conditions: 60±5°C, for 12 to 24 hours.
 - Expiration date: 12 months from sealing date, which is imprinted on the label.
- 4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
- 5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

Mounting Method

Soldering

Reflow soldering

Temperature profile for Pb soldering (example)

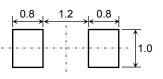


- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions.
 - Storage conditions before the second reflow soldering: 30°C, 60% RH (max)
- Make any necessary soldering corrections manually. (only once at each soldering point) Soldering iron: 25 W Temperature : 300°C or less

: within 3 s Time

Do not perform wave soldering.

Land pattern dimensions for reference only



Unit: mm

Cleaning

TOSHIBA

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES KAO CLEAN THROUGH 750H PINE ALPHA ST-100S : (made by ASAHI GLASS) : (made by KAO) : (made by ARAKAWA CHEMICAL

Precautions when Mounting

Do not apply force to the plastic part of the LED under high-temperature conditions. To avoid damaging the LED plastic, do not apply friction using a hard material. When installing the PCB in a product, ensure that the device does not come into contact with other emponents.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T18 (4-mm pitch)
- (2) Example

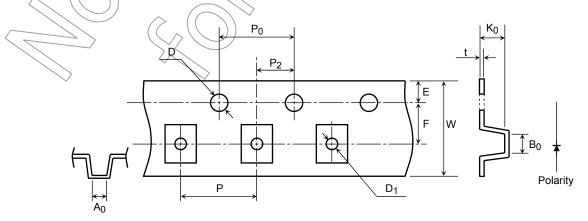
TLCBD1060 (T18)

— Tape type

Toshiba product No.

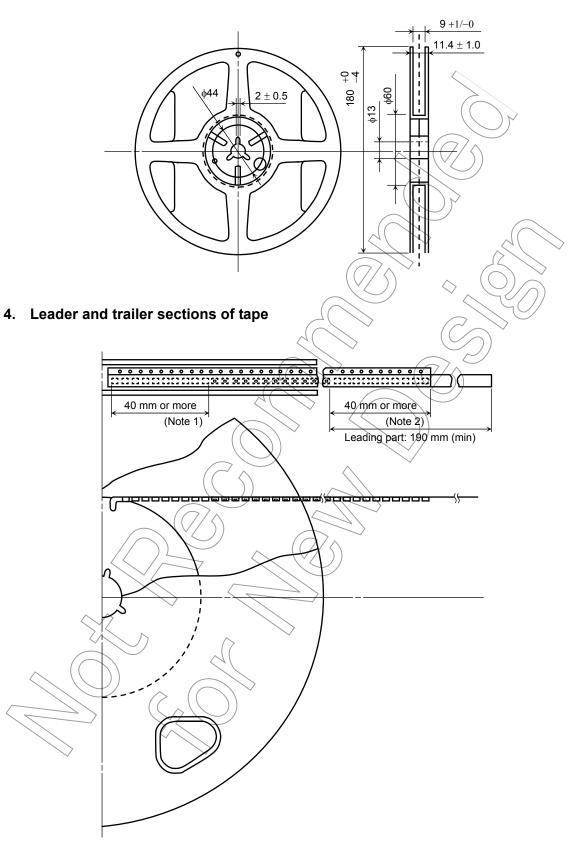
2. Tape dimensions

					$ \geq $	Unit: mm
Symbol	Dimension	Tolerance		Symbol	Dimension	Tolerance
D	/1.5)	+0.1/-0	\langle	(P_2)	2.0	±0.05
E	1.75	±0.1		W	8.0	±0.2
P ₀	4.0	±0.1		P	4.0	±0.1
t 🔨	∕ 0.2	±0.05		A ₀	1.5	±0.1
F 🗸	3,5	±0.05		∕ в₀	2.5	±0.1
D ₁	1.1	±0.1		K ₀	1.5	±0.1



3. Reel dimensions

Unit: mm



Note1: Empty trailer section Note2: Empty leader section

5. Packing display

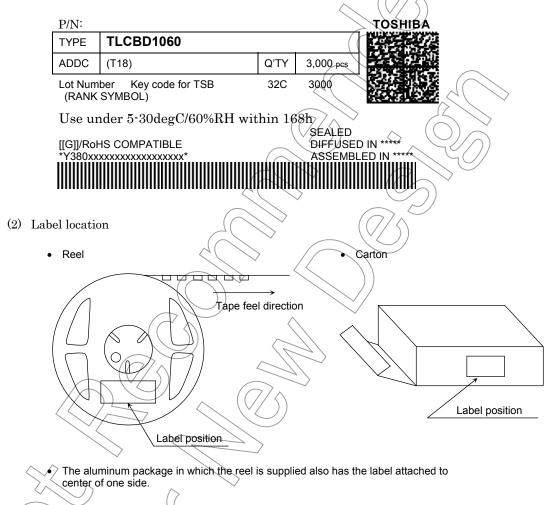
(1) Packing quantity

Reel	3,000 pcs
Carton	15,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

6. Label format

(1) Example: TLCBD1060 (T18)



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